

# Carrier Solutions

## Ultra-Low Total Thickness Variation (TTV) Glass Wafers

Our Ultra-Low TTV Glass Wafers have superior surface quality, flexible thickness, and can be available in a wide range of CTEs to meet customers’ most challenging requirements – from research & development phase to mass production.

### Applications

This glass wafer has one of the lowest TTV currently available and enables advanced semiconductor manufacturing including RF applications for 5G connectivity and hybrid bonding.

- Enables ultra-thinning of device wafer (final thickness <10µm)
- Allows more TTV tolerance for the adhesive layer to achieve same total stack TTV in semiconductor packaging
- Supports existing temporary bonding infrastructure to enable thinner device wafers
- Improves yield of Z-height sensitive processes

### Key Benefits

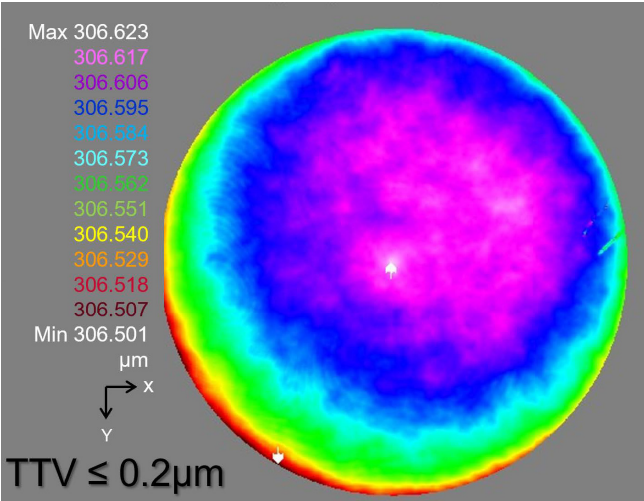
- TTV ≤0.2µm is available in sizes up to 200mm (3mm edge exclusion)
- TTV ≤0.4µm is available in sizes up to 300mm (2mm edge exclusion)
- This product is available now in a range of thicknesses for a variety of glass compositions.
- Available in across a range of CTEs from 3.4 to 12.6 ppm/°C
- High stiffness to help overcome CTE mismatch challenge
- Optically transparent enabling UV or IR based debond processes and laser mark serialization

### Options and Features

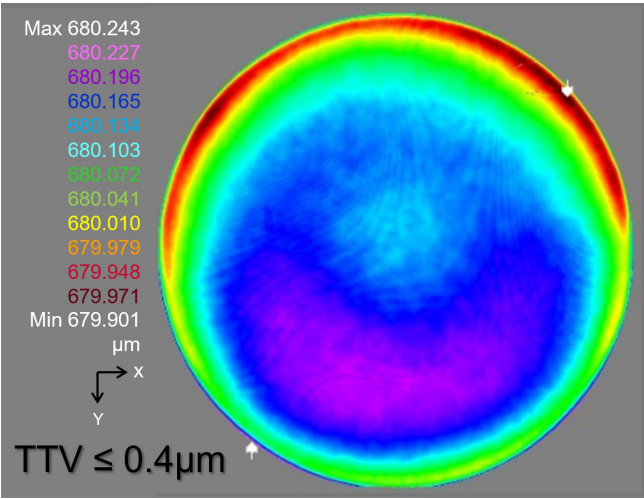
Diameter (mm)	100-300
Thickness (mm)	0.5 to 1.0
Edge Beveling	Radius (R) Type and Chamfer (C)
Surface Roughness (nm)	<1.0
Features	Semi-standard notch/flat or custom
Surface ID Marking	Semi-standard or custom

For other non-standard specifications please contact Corning.

200mm



300mm



Please contact for more information:  
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